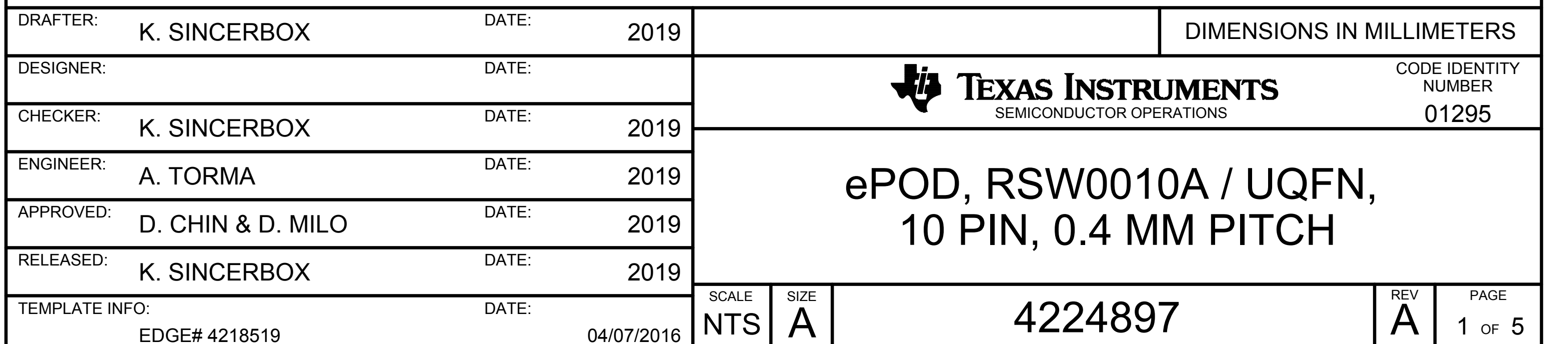
DATA BOOK
PACKAGE OUTLINE

PREVIEW



DRAFTER: K. SINCERBOX	DATE: 2019		DIMENSIONS IN MILLIMETERS
DESIGNER:	DATE:	TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295
CHECKER: K. SINCERBOX	DATE: 2019	ePOD, RSW0010A / UQFN, 10 PIN, 0.4 MM PITCH	
ENGINEER: A. TORMA	DATE: 2019		
APPROVED: D. CHIN & D. MILO	DATE: 2019		
RELEASED: K. SINCERBOX	DATE: 2019		
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	SCALE NTS, SIZE A, 4224897	REV A, PAGE 1 OF 5

B 1.45 1.35 A

PIN 1 INDEX AREA

1.85 1.75

0.55 0.45 NOTE 3

C SEATING PLANE

0.05 0.00

0.05 C

2X 0.8

SYMM

(0.13) TYP

3 5

9X 0.45 0.35

2 6

SYMM

6X 0.4

1 7

10X 0.25 0.15

0.07 C A B

0.05

10 8

0.55 0.45

PIN 1 ID

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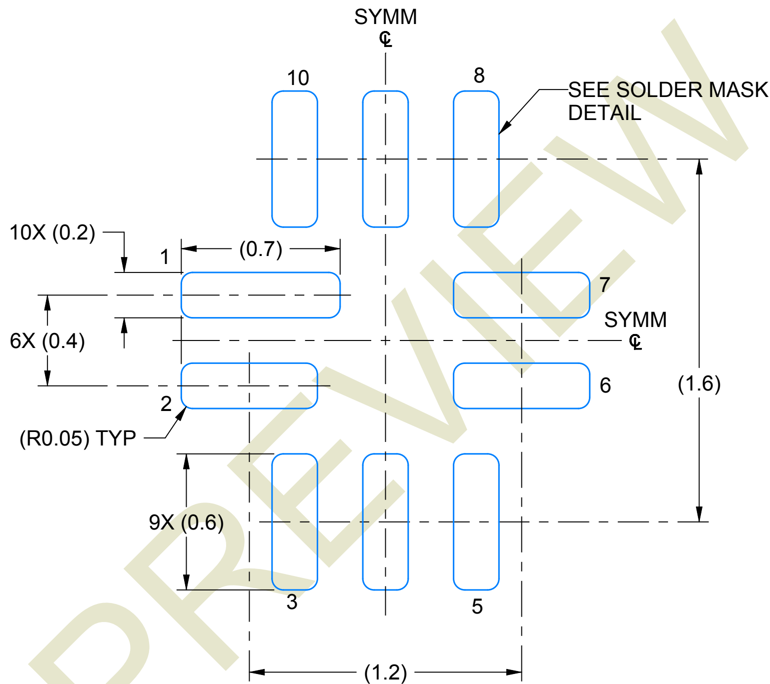
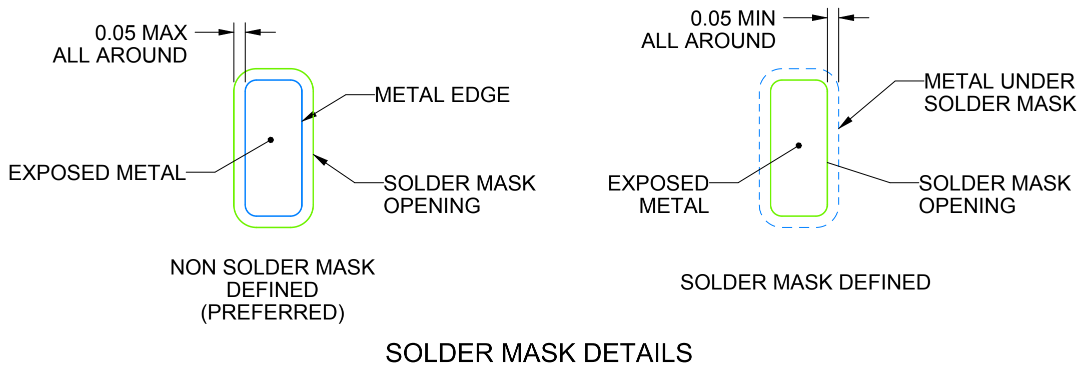
PREVIEW

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package complies to JEDEC MO-288 variation UDEE, except minimum package height.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 30X



SOLDER MASK DETAILS

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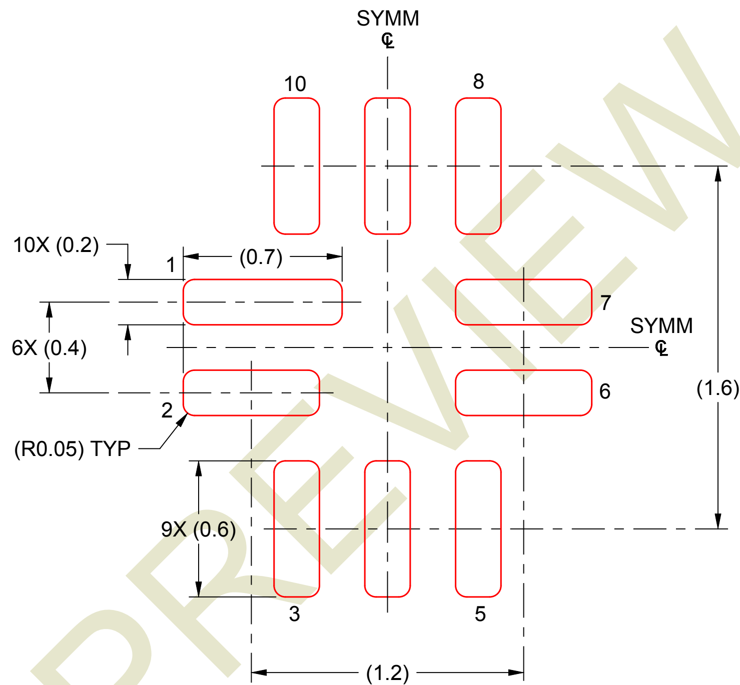
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 30X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2180189	2019	A. TORMA / K. SINCERBOX

PREVIEW